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Digital Test Interchange Format (DTIF)

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Contents

1. Overview 1

1.1 Scope 1
1.2 Purpose 1
1.3 Application 1

2. References 2

3. Definitions and acronyms 2

3.1 Definitions 2
3.2 Acronyms 4

4. Data organization overview of the DTIF standard environment 4

4.1 UUT Model Group 5
4.2 Stimulus and Response Group 5
4.3 Fault Dictionary Group 5
4.4 Probe Group 5

5. File specifications 6

5.1 HEADER file 7
5.2 STIMULUS file 9
5.3 PO_RESPONSE file 10
5.4 PI_NAMES file 11
5.5 PO_NAMES file 12
5.6 MAIN_MODEL file 13
5.7 COMPONENT_TYPE file 14
5.8 USER_NODE file 15
5.9 INPUT_PIN_NAMES file 16
5.10 OUTPUT_PIN_NAMES file 17
5.11 NEAR_FROMS_POINTERS file 18
5.12 NEAR_FROMS file 19
5.13 EVENT file 20
5.14 SETTLED_STATE_ONLY file 22
5.15 SETTLED_STATE_&_PULSES file 23
5.16 NODE_SOURCE file 25
5.17 STEPS file 26
5.18 F.D._POPATS file 27
5.19 F.D._FAULT_SIGNATURES file 28
5.20 F.D._PRINT_STRINGS file 30
5.21 TRISTATE_FROMS_POINTERS file 32
5.22 TRISTATE_FROMS file 33
5.23 PSEUDOPI_NAMES file 34
5.24 TIMING_SETS file 35
5.25 TIMING_PER_PATTERN file 37
5.26 PHASE_CONNECTIONS file 38
5.27 AUXILIARY_PIN_NAMES file 39
5.28 PI_FORMATS file 40
5.29 FORMAT_ATTRIBUTES file 41

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5.30 F.D. _CROSS_REFERENCE file 42
5.31 PROBETAG_ DEFINITIONS file 43
5.32 PROBETAG_ASSIGNMENTS file 45
5.33 BURSTS file 46
5.34 STIMULUS_TEXT file 47
5.35 NODE_NAMES file 48
5.36 EVENTS_INIT file 49
5.37 EQUIV_FAULTS file 51
5.38 PROBE_DETECTION file 52
5.39 F.D._EQUIV_SETS file 53

6. Conformance 54

6.1 End-to-end test 54
6.2 Diagnostic test using fault dictionary 54
6.3 Diagnostic test using probe 56

Annex A (informative) Implementation overview 59

Annex B (informative) DTIF dependency diagrams 61

Annex C (informative) Example circuit 66

Annex D (informative) IEEE List of Participants 100

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Digital Test Interchange Format (DTIF)

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IEEE Std 1445-1998	93/321/FDIS	93/328/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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IEEE Standard for Digital Test Interchange Format (DTIF)

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IEEE Standards Coordinating Committee 20 on Test and Diagnosis for Electronic Systems

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Abstract: The information content and the data formats for the interchange of digital test program data between digital automated test program generators (DATPGs) and automatic test equipment (ATE) for board-level printed circuit assemblies are defined. This information can be broadly grouped into data that defines the following: UUT Model, Stimulus and Response, Fault Dictionary, and Probe.
Keywords: automatic test equipment (ATE), digital automated test program generator (DATPG), digital test interchange format (DTIF), Fault Dictionary data

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IEEE Introduction

[This introduction is not part of IEEE Std 1445-1998, IEEE Standard for Digital Test Interchange Format (DTIF).]

A digital automated test program generator (DATPG) produces test pattern and diagnostic data that can be used for testing printed circuit assemblies on automatic test equipment (ATE). The use of several DATPGs, all with individual output formats, created a need for many unique post-processors to be developed and maintained for the life of the ATE. These post-processors supported the link from specific DATPGs to specific testers. The proliferation of unique formats and post-processors created logistical support problems and therefore identified a need for standardization. A DATPG and ATE independent output data format is required to limit the number of post-processors (one for each ATE) requiring life cycle support. The digital test interchange format (DTIF) was chosen because of its wide use and because it was becoming known in industry as the de facto standard.

This document provides the basis to standardize digital test information for use on ATE. The digital test information consists of the unit under test (UUT) Model information, Stimulus and Response data, Fault Dictionary data, and Probe data.

DTIF is unique from other standards such as IEEE P1450 (Draft 0.95, dated July 1998),[1] Draft Standard Test Interface Language (STIL) for Digital Test Vector Data, and IEEE Std 1029.1-1991, IEEE Standard for Waveform and Vector Exchange Specification (WAVES). STIL is being developed to standardize the output interface of existing computer-aided engineering (CAE) tools with the input interface of ATE for integrated circuit (IC) testing only. WAVES is a hardware descriptive language used for defining stimulus and response, and their associated timing for IC/board-level design. Neither STIL nor WAVES provides for board-level fault diagnostics.

A future revision of this standard will consider the use of the information model.

1 IEEE P1450 is an IEEE authorized standards project that was not approved by the IEEE-SA Standards Board at the time this publication went to press. For information about obtaining the draft, contact the IEEE.

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Digital Test Interchange Format (DTIF)

1. Overview

The digital test interchange format (DTIF) is designed to provide a mechanism for digital test data interchange independent of specific digital automated test program generators (DATPGs) and test systems. The DTIF provides a neutral database for the development and delivery of digital simulation based test program sets (TPSs). DTIF functionally supports the unit under test (UUT) Model, Stimulus and Response, Fault Dictionary, and Probe databases.

1.1 Scope

This standard defines the information content and the data formats for the interchange of digital test program data between DATPGs and automatic test equipment (ATE) for board-level printed circuit assemblies. This information can be broadly grouped into data that defines the following:

a) UUT Model;
b) Stimulus and Response;
c) Fault Dictionary;
d) Probe.

1.2 Purpose

The purpose of this standard is to provide a standard output format for test data generated by a DATPG. A DATPG produces test patterns and fault diagnostic data for ATE. This data is used in applications such as board-level assemblies where diagnostic data interchange is important.

1.3 Application

This standard is primarily intended for use by digital simulator developers/maintainers and TPS developers/maintainers.

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2. References

This standard shall be used in conjunction with the following standards. When the following standards are superseded by an approved revision, the revision shall apply.

ANSI X3.4-1986 (Reaff 1997), Information Systems—Coded Character Sets—7-Bit American National Standard Code for Information Interchange (7-Bit ASCII).[1]

IEEE Std 100-1996, IEEE Standard Dictionary of Electrical and Electronics Terms.[2]

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